



## Final Product Change Notification **Update**

202103024F01U01 : S12VR64/48 FAB SITE EXPANSION (NXP-ATMC to TSMC10)

**Note:** This notice is NXP Company Proprietary.

**Issue Date:** Jun 15, 2021 **Effective date:** Jun 16, 2021

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### Management summary

This FPCN is updated to inform users that the Reference Manual for the product has been updated to include mask set information of TSMC10 fab site. Please see section "Update Information \*" for further details.

### Change Category

- |  |  |  |   |   |
|--|--|--|---|---|
| <input type="checkbox"/> Wafer Fab Process             | <input type="checkbox"/> Assembly Process  | <input type="checkbox"/> Product Marking           | <input type="checkbox"/> Test Process   | <input type="checkbox"/> Design                         |
| <input type="checkbox"/> Wafer Fab Materials           | <input type="checkbox"/> Assembly Materials  | <input type="checkbox"/> Mechanical Specification  | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Errata                         |
| <input checked="" type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location   | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Location  | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware                      | <input checked="" type="checkbox"/> Other: Reference Manual and Errata updated to include TSMC10 mask set information. |  |   |   |

## PCN Overview

### Description

NXP Semiconductors is announcing the introduction of Taiwan Semiconductor Manufacturing Company Fab 10 (TSMC10), Shanghai, China as a dual source wafer manufacturing location for the S912VR64/48.

NXP Semiconductors requires the use of Flex part numbers to maximize supply continuity. Without the use of Flex part numbers, backlog will have to be converted from one fab sourced device to another fab sourced device as capacity dictates.

The current Reference Manual rev4.3 will be updated by adding TSMC10 mask set (0P79C) in sections 1.61 Part ID Assignments, 1.11 Module Device level Dependencies and Part Ordering Information. Please see the attached file "RM Update For MC9S12VR to Include TSMC10". An update to this PCN will be issued when the final version of the Reference Manual has been added into NXP.com.

Errata for S912VR64/48 has been updated and can be found at

[https://www.nxp.com/products/processors-and-microcontrollers/additional-mpu-mcus-architectures/s12-magniv-mixed-signal-mcus/s12vr-mixed-signal-mcu-for-automotive-industrial-relay-based-motor-control:S12VR?fsp=1&tab=Documentation\\_Tab](https://www.nxp.com/products/processors-and-microcontrollers/additional-mpu-mcus-architectures/s12-magniv-mixed-signal-mcus/s12vr-mixed-signal-mcu-for-automotive-industrial-relay-based-motor-control:S12VR?fsp=1&tab=Documentation_Tab)

Corresponding ZVEI Delta Qualification Matrix ID: SEM-DS-02, SEM-PW-08, SEM-PW-13

#### **Reason**

The Fab manufacturing site capacity expansion to TSMC10 will improve NXP's ability to meet increasing customer demand and still maintain supply from the original Fab (NXP-ATMC).

#### **Identification of Affected Products**

Top Side Marking

The mask marking for TSMC10 will reflect P79C, while the mask marking for ATMC will remain N59H.

### **Product Availability**

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#### **Sample Information**

Samples are available from Apr 20, 2021

Please see the attachment "S12VR64\_48\_ATMC to TSMC10 Fab Expansion\_FPCN\_Supplement" file for sample part numbers available for ordering.

#### **Production**

Planned first shipment Jul 05, 2021

### **Anticipated Impact on Form, Fit, Function, Reliability or Quality**

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No Impact on form, fit, function, reliability or quality

#### **Data Sheet Revision**

A new datasheet will be issued

#### **Disposition of Old Products**

Fab Expansion. No Depletion of Inventory required.

### **Timing and Logistics**

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In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Jul 15, 2021.

### **Update Information**

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The Reference Manual rev4.3 has been updated to rev4.4 by adding TSMC10 mask set (0P79C) in sections 1.61 Part ID Assignments, 1.11 Module Device level Dependencies and Part Ordering Information.

This document is attached to this FPCN update or can be downloaded from

[https://www.nxp.com/products/processors-and-microcontrollers/additional-mpu-mcus-architectures/s12-magniv-mixed-signal-mcus/s12vr-mixed-signal-mcu-for-automotive-industrial-relay-based-motor-control:S12VR?fsp=1&tab=Documentation\\_Tab](https://www.nxp.com/products/processors-and-microcontrollers/additional-mpu-mcus-architectures/s12-magniv-mixed-signal-mcus/s12vr-mixed-signal-mcu-for-automotive-industrial-relay-based-motor-control:S12VR?fsp=1&tab=Documentation_Tab)

### **Contact and Support**

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For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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NXP Quality Management Team.

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<b>Affected OPN</b>	<b>12NC</b>
S9S12VR48AF0CLC	935318165557
S9S12VR48AF0CLCR	935318165528
S9S12VR48AF0CLF	935324813557
S9S12VR48AF0CLFR	935324813528
S9S12VR48AF0MLC	935312205557
S9S12VR48AF0MLCR	935312205528
S9S12VR48AF0MLF	935317776557
S9S12VR48AF0MLFR	935317776528
S9S12VR48AF0VLC	935315364557
S9S12VR48AF0VLCR	935315364528
S9S12VR48AF0VLF	935317975557
S9S12VR48AF0VLFR	935317975528
S9S12VR64AF0CLC	935323493557
S9S12VR64AF0CLF	935322011557
S9S12VR64AF0MLC	935311241557
S9S12VR64AF0MLCR	935311241528
S9S12VR64AF0MLF	935317864557
S9S12VR64AF0MLFR	935317864528
S9S12VR64AF0VLC	935318018557
S9S12VR64AF0VLF	935322012557